

N109 W13300 ELLSWORTH DRIVE GERMANTOWN, WI 53022  
262-253-5900 FAX 262-253-5919

**DESCRIPTION:**

*ResinLab® EP1026T3 Clear* is a two-part unfilled epoxy adhesive designed for high-speed bonding of metals, ceramics, and most plastics. It cures to a tough, semi-rigid material. The thixotropic paste consistency prevents running and sagging. This formula will have good resistance to water, salt spray, inorganic acids and bases, and most organic solvents.

*EP1026T3 Clear* was formulated to a 1A:1B volume mix ratio for use in side-by-side dispensing cartridges and meter/mix and dispense equipment.

Handling cure is normally achieved at room temperature within 20-30 minutes with full cure in 24 hours. Because of the fast and exothermic reaction process, this product should only be used in small volumes. *EP1026T3 Clear* can be used at higher temperature ranges. This range listed is typical of most mercaptan based systems. Testing is essential for validation of functional specifications based on the operating temperature ranged used.

**TYPICAL PROPERTIES:**

All properties given are at 25 °C unless otherwise noted.

<b>Property:</b>	<b>Value:</b>	<b>Test Method or Source:</b>
<b>Color</b>	Pale Amber	Visual
<b>Mix Ratio</b>	Part A to Part B	Calculated
<b>Mix Ratio by weight</b>	1.02 to 1	
<b>Mix Ratio by volume</b>	1 to 1	
<b>Cure Schedule</b>	24 hrs @ 25 °C	
<b>Viscosity - Part A</b>	720,000 cP	Rheometer parallel plate 25mm @ 1/s
<b>Viscosity - Part B</b>	560,000 cP	455300006291
<b>Viscosity - Mixed</b>	485,000 cP	
<b>Specific Gravity - Part A</b>	1.17	Calculated
<b>Specific Gravity - Part B</b>	1.17	
<b>Specific Gravity - Mixed</b>	1.17	
<b>Pot Life defined as the time it takes for initial mixed viscosity to double</b>	5 minutes	Rheometer parallel plate 25mm @1/s 455300006291
<b>Hardness</b>	80 Shore D	455300006287/ASTM D2240
<b>Glass Transition Temperature/Tg</b>	30 °C	453560822409 by DSC
<b>Water Absorption</b>	0.78 %	24 hr immersion 457561824543/ASTM D570
<b>Peak Exotherm</b>	148 °C after 7 minutes for 40 mL sample	455300005593 by Type K thermocouple
<b>Tensile Properties:</b>		4535601224470/ASTM D638
<b>Strength</b>	3,000 psi	
<b>Elongation</b>	20 %	
<b>Modulus</b>	240,000 psi	

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<b>Property:</b>	<b>Value:</b>	<b>Test Method or Source:</b>
<b>Compressive Properties:</b>		4535601224467/ASTM D695
Yield Strength	26,000 psi	
Ultimate Strength	39,000 psi	
Modulus	183,000 psi	
<b>Flame Resistance Tested at ResinLab, not UL Certified</b>	Passes with HB Rating @ 6.0 mm	45376013225560/UL94HB
<b>Volume Resistivity</b>	3.60 x 10 <sup>14</sup> ohm-cm	455300006612/ASTM D257 @ 21 °C @ 20 %RH
<b>Surface Resistivity</b>	8.3 x 10 <sup>13</sup> ohm/sq	455300006612/ASTM D257 @ 21 °C @ 20 %RH
<b>Dielectric Constant &amp; Dissipation Factor</b>		455300006513/ASTM D150
@ 100 Hz	4.6, 0.05	
@ 100 kHz	4.0, 0.05	
<b>AC Dielectric Strength</b>	410 kV/mm *	ASTM D149 Method A, immersed in ASTM D3487 Type II Oil
<b>Coefficient of Thermal Expansion by TMA</b>		455300005340/ASTM E831 TMA, 5 °C/min
below Tg	49 ppm/°C	
above Tg	216 ppm/°C	
<b>Operating Temperature Range</b>	-40 to 80 °C**	
<b>Relative Thermal Index (RTI)</b>	50 °C	UL746B, Table 7.1 Generic Value Based on Composition

\* Asterisk denotes values considered typical to associated resin systems or extrapolated from other test results.

\*\* Operating Temperature Range is based on average design requirements and is not intended as a guarantee of suitability for all applications operating at that temperature.

\*\*\* This TDS contains values that have been updated. The values reported in this technical data sheet are typical values of the product, and are highly dependent on test conditions and methodology. We actively seek the most precise and accurate ways to measure and interpret performance of our products, and to update estimated values with measured values. The formula has not been revised or changed in any way. Although the values on paper have changed, you can expect the same performance of the product.

**Additional Performance Data – Lap Shear Adhesion, 4535601224468/ASTM D1002:**

<b>Substrate Type</b>	<b>Strength</b>	<b>Test Temperature</b>	<b>Cure Schedule</b>	<b>Bond Line Thickness</b>
Al to Al	800 psi	23 °C	24 hr @ 25 °C	0.010 "
Al to Al	2,600 psi	23 °C	30 min 25 °C + 1 hr @ 100 °C	0.010 "

**INSTRUCTIONS:**

1. Bring to room temperature prior to use.

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2. Cartridge format: Mixer should be attached keeping the cartridge vertical and any air pocket purged this way. After the mixer contains material, the mixer tip can be dropped to dispense pre-bleed amount. Attach a new static mixer with each cartridge, then pre-bleed the first 3 inches of dispensed material or until a uniform color is obtained. Maintain adequate velocity during dispensing to ensure complete mixing.
3. Bulk format: stir until homogeneous weigh and mix parts A and B accurately and thoroughly, scraping sides of container often. Do not pour from mixing container, transfer to a new container as residual unmixed material may cause a tacky spot on the surface of the casting. Maintain adequate velocity during dispensing to ensure complete mixing.
4. Allow to cure undisturbed until product is fully gelled or tack-free to the touch.
5. Clean up uncured resin with suitable organic solvent such as MEK or acetone.

**SHELF LIFE AND STORAGE:**

12 months at 25 °C.  
Specialty packaging may be less.

Many epoxy resin systems are prone to crystallization as epoxy resin is a super-cooled fluid. This condition may give the product a gritty or grainy appearance (or hazy in clear products). Products in this state will not usually cure to normal and expected properties. In extreme cases it may appear solid and cured. Fluctuating temperatures (within 5 to 50 °C) aggravate this phenomenon. Heating the individual component to 50 to 60 °C while stirring can usually restore products to original state. Storage at 25 +/- 10 °C is optimum for most products.